Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	0	((solid near5 resin) same mold$3 same (cavity recess groove) same ((lower bottom) near5 mold) same ((upper top) near5 mold) same melt$3 same (immers$3 plac$3 put$3) same encapsulat$3).clm.	US-PGPUB	OR	ON	2006/01/11 17:28
L5	1	((solid near5 resin) same mold$3 same (cavity recess groove) same ((lower bottom) near5 mold) same ((upper top) near5 mold) same melt$3). clm.	US-PGPUB	OR	ON	2006/01/11 17:31
L7	2	((solid near5 resin) and mold$3 and (cavity recess groove) and ((lower bottom) near5 mold) and((upper top) near5 mold) and melt$3).clm.	US-PGPUB	OR	ON	2006/01/11 17:31

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	56842	(solid near5 resin)	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/11 13:24
L2	5853	1 and cavity	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/11 13:24
L3	3206	2 and mold	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/11 13:25
L4	1898	3 and melt$3	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/11 13:25
L5	262	4 and semiconductor	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/11 13:20
L6	22140	(solid near5 resin)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 13:24
L7	5853	2 and cavity	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/11 13:24
L8	263	6 and cavity	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 13:25
L9	150	8 and mold	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 13:25
L10	36	9 and melt$3	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/11 13:25